

## Corporate names revised in the documents

On March 1st 2015, system LSI businesses of Fujitsu Limited and Panasonic Corporation have been consolidated and transferred to Socionext Inc.

The corporate names "Fujitsu Semiconductor Limited" and "Panasonic" all in this document have been revised to the "Socionext".

Thank you for your cooperation and understanding of this notice.

March 2, 2015

Socionext Inc.

<http://www.socionext.com/en/>

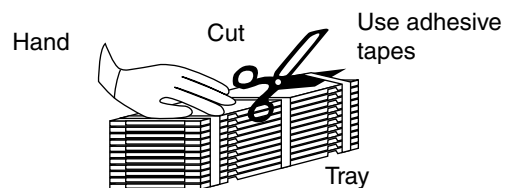
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# Packing handling precautions

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1. Because outer boxes gradually weaken during storage as a result of moisture, stacking, etc., inventory should be handled on a first-in, first-out basis.
2. Although the IC packing materials (such as tubes) are designed to protect against electrostatic damage, full precautions against electrostatic damage must be taken when removing the products from their packing.
3. Handle the inner and outer boxes gently. Rough handling can dislodge the tubes stoppers, allowing the products to fall out of the tubes and possibly bend their leads. Rough handling of boxes containing ceramic packages in particular can cause chips, cracks, or leak defects.
4. Because the inner and outer boxes are made of corrugated cardboard, do not allow them to become wet. Do not store the boxes outside or in a hot and humid location under any circumstances.
5. Do not throw, drop or otherwise roughly handle the outer boxes (corrugated cardboard boxes) containing products under any circumstances.
6. QFPs are packed in trays, but it is very easy to accidentally bend their leads when removing them from their original packing and placing them in other packing. Therefore, strictly observe the following items.

- a) When cutting the binding tape, hold the trays securely in place with one hand.

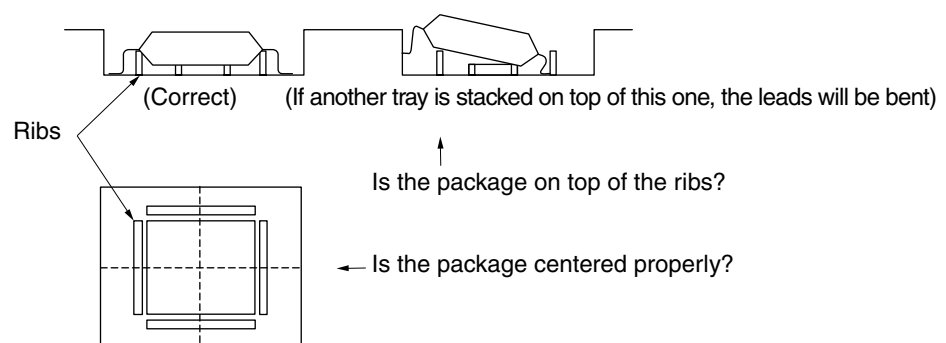


- b) Hold the trays firmly in place while removing the tape so that the trays do not shift position. (If the trays shift, the packed ICs may be dislodged and the leads may bend.)
- c) Check after packing the packages

Before stacking the trays containing the IC packages, check the following points.

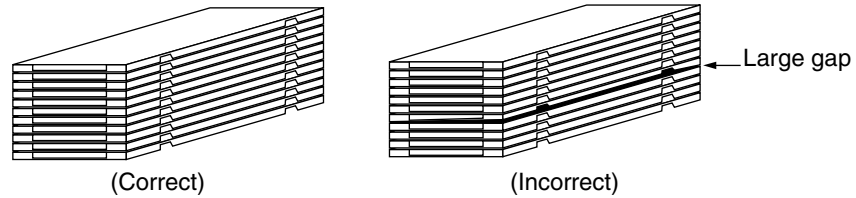
- Make sure that the packages are properly positioned on the ribs.
- If any packages are not positioned on the ribs, , check for bent leads and then reposition the packages.

**Note:** When handling the packages, make sure to take electrostatic countermeasures, such as wearing finger sleeves or a grounded wrist strap. Use air tweezers, and avoid touching the leads if possible.



## d) Check after stacking the trays

- Make sure that there are no abnormal gaps between the stacked trays.
- Handle the stacked trays carefully when using packing tape or packing bands to secure the trays. (Secure the trays only after making sure that there are no gaps.)



7. When removing stoppers from containers, be careful not to let the stopper jump out of the container.
8. A container, coated with antistatic, may be sticky.
9. Heat resistant tray has a label entitled "HT" or "heat proof temperature" (e.g. 125 °C MAX). The heat resistant tray allows 125 °C heat being applied for 24 hours. It may cause warp on heating or cooling. To minimize the warp, it is be heated or cooled on a flat surface. Avoid the abrupt cooling.